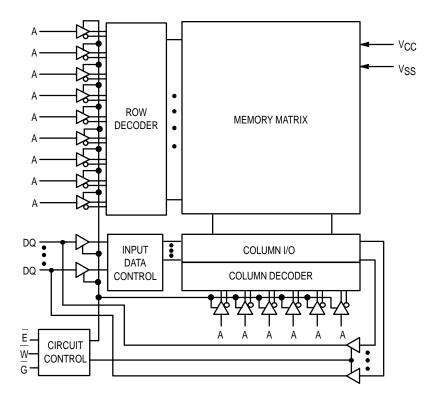
32K x 8 Bit Fast Static RAM

The MCM6206BA is a 262,144 bit static random access memory organized as 32,768 words of 8 bits. Static design eliminates the need for external clocks or timing strobes, while CMOS circuitry reduces power consumption and provides for greater reliability.

This device meets JEDEC standards for functionality and pinout, and is available in plastic small—outline J—leaded packages.

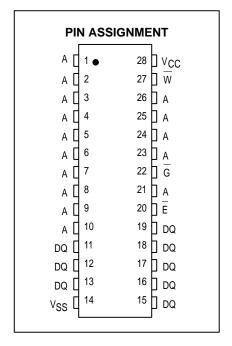
- Single 5 V ± 10% Power Supply
- Fully Static No Clock or Timing Strobes Necessary
- Fast Access Times: 12/15/20/25 ns
- Equal Address and Chip Enable Access Times
- Output Enable (G) Feature for Increased System Flexibility and to Eliminate Bus Contention Problems
- Low Power Operation: 125 140 mA Maximum AC
- Fully TTL Compatible Three State Output

BLOCK DIAGRAM



MCM6206BA





PIN NAMES
A Address Input DQ Data Input/Data Output W Write Enable G Output Enable E Chip Enable VCC Power Supply (+ 5 V) VSS Ground

REV 1 10/9/96



TRUTH TABLE (X = Don't Care)

Е	G	W	Mode	V _{CC} Current	Output	Cycle
Н	Х	Х	Not Selected	I _{SB1} , I _{SB2}	High-Z	_
L	н	Н	Output Disabled	^I CCA	High–Z	_
L	L	Н	Read	^I CCA	D _{out}	Read Cycle
L	Х	L	Write	ICCA	High-Z	Write Cycle

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Power Supply Voltage	Vcc	- 0.5 to + 7.0	V
Voltage Relative to VSS For Any Pin Except VCC	V _{in} , V _{out}	- 0.5 to V _{CC} + 0.5	>
Output Current	l _{out}	± 20	mA
Power Dissipation	PD	1.0	W
Temperature Under Bias	T _{bias}	- 10 to + 85	°C
Operating Temperature	TA	0 to + 70	°C
Storage Temperature—Plastic	T _{stg}	- 55 to + 125	°C

NOTE: Permanent device damage may occur if ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to RECOMMENDED OPER-ATING CONDITIONS. Exposure to higher than recommended voltages for extended periods of time could affect device reliability.

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high-impedance circuit.

This CMOS memory circuit has been designed to meet the dc and ac specifications shown in the tables, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow of at least 500 linear feet per minute is maintained.

DC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, T_A = 0 \text{ to } 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min	Тур	Max	Unit
Supply Voltage (Operating Voltage Range)	Vcc	4.5	5.0	5.5	V
Input High Voltage	VIH	2.2		V _{CC} + 0.3**	V
Input Low Voltage	V _{IL}	- 0.5*	_	0.8	V

^{*} V_{IL} (min) = -0.5 V dc; $\overline{V_{IL}}$ (min) = -2.0 \overline{V} ac (pulse width ≤ 20 ns)

DC CHARACTERISTICS

Parameter	Symbol	Min	Max	Unit
Input Leakage Current (All Inputs, V _{in} = 0 to V _{CC})	l _{lkg(l)}	_	± 1	μΑ
Output Leakage Current (E = V _{IH} or G = V _{IH} , V _{Out} = 0 to V _{CC})	l _{lkg(O)}	_	± 1	μΑ
Output High Voltage (I _{OH} = - 4.0 mA)	Voн	2.4		V
Output Low Voltage (I _{OL} = 8.0 mA)	VOL		0.4	V

POWER SUPPLY CURRENTS

Parameter	Symbol	- 12	- 15	- 20	- 25	Unit
AC Active Supply Current ($I_{out = 0 \text{ mA}}$, $V_{CC} = Max$, $f = f_{max}$)	ICCA	140	135	130	125	mA
AC Standby Current (E = V _{IH} , V _{CC} = Max, f = f _{max})	I _{SB1}	40	35	35	30	mA
CMOS Standby Current (V $_{CC}$ = Max, f = 0 MHz, E \geq V $_{CC}$ - 0.2 V V $_{in} \leq$ V $_{SS}$ + 0.2 V, or \geq V $_{CC}$ - 0.2 V)	I _{SB2}	10	10	10	10	mA

CAPACITANCE (f = 1 MHz, dV = 3 V, $T_A = 25$ °C, Periodically sampled rather than 100% tested)

Characteristic	Symbol	Max	Unit
Address Input Capacitance	C _{in}	6	pF
Control Pin Input Capacitance (E, G, W)	C _{in}	8	pF
I/O Capacitance	C _{I/O}	8	pF

^{**} V_{IH} (max) = V_{CC} + 0.3 V dc; V_{IH} (max) = V_{CC} + 2.0 V ac (pulse width \leq 20 ns)

AC OPERATING CONDITIONS AND CHARACTERISTICS

 $(V_{CC} = 5.0 \text{ V} \pm 10\%, T_A = 0 \text{ to} + 70^{\circ}\text{C}, \text{ Unless Otherwise Noted})$

Input Timing Measurement Reference Level 1.5 V	Output Timing Measurement Reference Level 1.5 V
Input Pulse Levels 0 to 3.0 V	Output Load Figure 1a Unless Otherwise Noted
Input Rise/Fall Time 5 ns	

READ CYCLE (See Note 1)

		-	12	– 15		-	20	-:	25		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Note s
Read Cycle Time	t _{AVAV}	12	_	15	_	20	_	25	_	ns	2
Address Access Time	t _{AVQV}	_	12	_	15	_	20	_	25	ns	
Enable Access Time	^t ELQV	_	12	_	15	_	20	_	25	ns	3
Output Enable Access Time	tGLQV	_	6	_	8	_	10	_	12	ns	
Output Hold from Address Change	tAXQX	3	_	3	_	3	_	3	_	ns	4,5,6
Enable Low to Output Active	^t ELQX	4	_	4	_	4	_	4	_	ns	4,5,6
Enable High to Output High–Z	^t EHQZ	_	7	_	8	_	9	_	10	ns	4,5,6
Output Enable Low to Output Active	tGLQX	0	_	0	_	0	_	0	_	ns	4,5,6
Output Enable High to Output High–Z	^t GHQZ	_	6	_	7	_	8	_	10	ns	4,5,6
Power Up Time	^t ELICCH	0	_	0	_	0		0	_	ns	
Power Down Time	^t EHICCL	_	12	_	15	_	20	_	25	ns	

NOTES:

- 1. W is high for read cycle.
- 2. All timings are referenced from the last valid address to the first transitioning address.
- 3. Addresses valid prior to or coincident with E going low.
- 4. At any given voltage and temperature, tehoz (max) is less than telox (min), and to to to device and from device to device.
- 5. Transition is measured ± 500 mV from steady–state voltage with load of Figure 1b.
- 6. This parameter is sampled and not 100% tested.
- 7. Device is continuously selected (E = V_{IL} , G = V_{IL}).

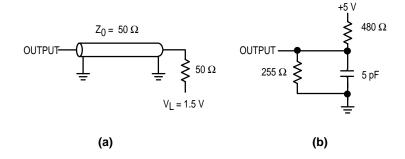


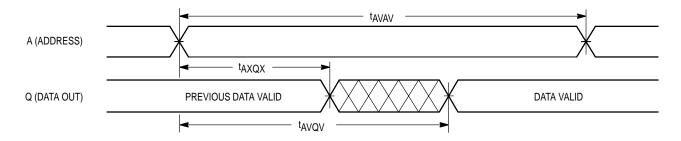
Figure 1. AC Test Loads

TIMING LIMITS

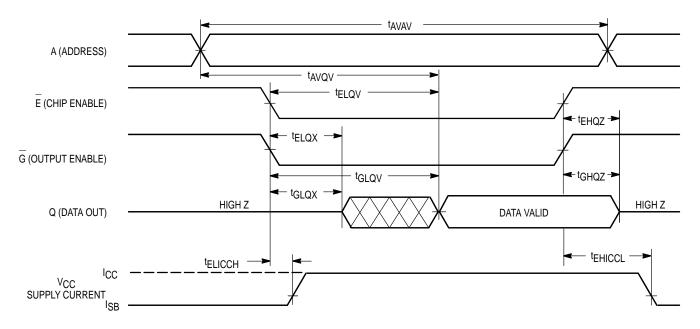
The table of timing values shows either a minimum or a maximum limit for each parameter. Input requirements are specified from the external system point of view. Thus, address setup time is shown as a minimum since the system must supply at least that much time. On the other hand, responses from the memory are specified from the device point of view. Thus, the access time is shown as a maximum since the device never provides data later than that time.

MOTOROLA FAST SRAM MCM6206BA

READ CYCLE 1 (See Note 7)



READ CYCLE 2 (See Note 3)



MCM6206BA MOTOROLA FAST SRAM

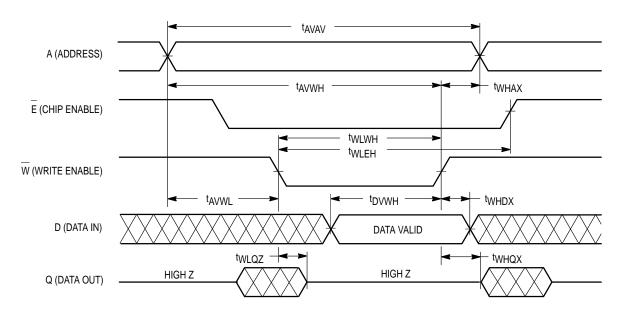
WRITE CYCLE 1 (W Controlled, See Notes 1 and 2)

		-	12	-	15	- :	20	-:	25		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	tAVAV	12	_	15	_	20	_	25	_	ns	3
Address Setup Time	t _{AVWL}	0	_	0	_	0	_	0	_	ns	
Address Valid to End of Write	^t AVWH	10	_	12	_	15	_	20		ns	
Write Pulse Width	tWLWH, tWLEH	10	_	12	_	15	_	20	_	ns	
Write Pulse Width, G High	tWLWH, tWLEH	10	_	10	_	12	_	15	_	ns	4
Data Valid to End of Write	^t DVWH	6	_	7	_	8	_	10	_	ns	
Data Hold Time	tWHDX	0	_	0	_	0	_	0	_	ns	
Write Low to Output High–Z	tWLQZ	_	6	_	7	_	8	_	10	ns	5,6,7
Write High to Output Active	tWHQX	2	_	2	_	2	_	2	_	ns	5,6,7
Write Recovery Time	tWHAX	0	_	0	_	0	_	0		ns	

NOTES:

- 1. A write occurs during the overlap of E low and W low.
- 2. If G goes low coincident with or after W goes low, the output will remain in a high impedance state.
- 3. All timings are referenced from the last valid address to the first transitioning address.
- 4. If $G \ge V_{IH}$, the output will remain in a high impedance state.
- 5. At any given voltage and temperature, t_{WLQZ} (max) is less than t_{WHQX} (min), both for a given device and from device to device.
 6. Transition is measured ±500 mV from steady–state voltage with load of Figure 1b.
- 7. This parameter is sampled and not 100% tested.

WRITE CYCLE 1 (W Controlled, See Notes 1 and 2)



MOTOROLA FAST SRAM **MCM6206BA**

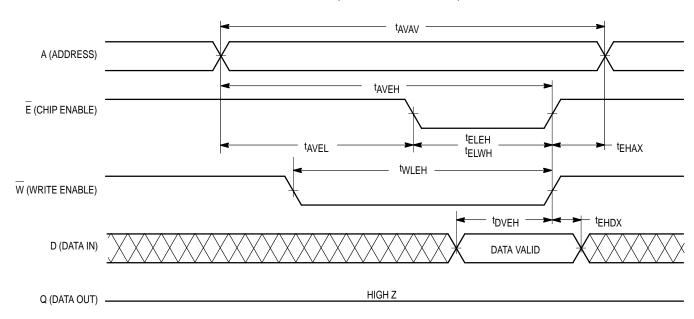
WRITE CYCLE 2 (E Controlled, See Note 1)

		_	12	_	15	-:	20	-:	25		
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit	Notes
Write Cycle Time	t _{AVAV}	12	_	15	_	20	_	25	_	ns	
Address Setup Time	^t AVEL	0	_	0	_	0	_	0	_	ns	
Address Valid to End of Write	^t AVEH	10	_	12	_	15	_	20	_	ns	
Enable to End of Write	^t ELEH [,] ^t ELWH	9	_	10	_	12	_	15	_	ns	3,4
Data Valid to End of Write	^t DVEH	6	_	7	_	8	_	10	_	ns	
Data Hold Time	tEHDX	0	_	0	_	0	_	0	_	ns	
Write Recovery Time	^t EHAX	0	_	0		0	_	0	_	ns	

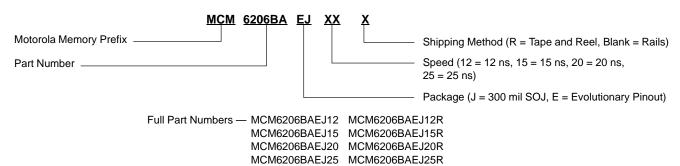
NOTES:

- 1. A write occurs during the overlap of E low and W low.
- 2. All timings are referenced from the last valid address to the first transitioning address.
- 3. If <u>E</u> goes low coincident with or after W goes low, the output will remain in a high impedance state.
- 4. If E goes high coincident with or before W goes high, the output will remain in a high impedance state.

WRITE CYCLE 2 (E Controlled, See Note 1)



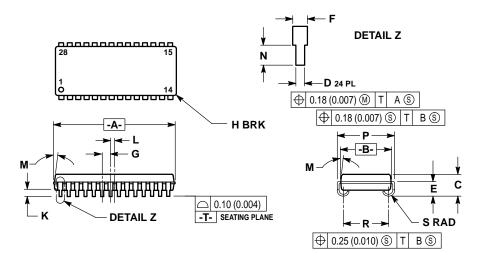
ORDERING INFORMATION (Order by Full Part Number)



MCM6206BA MOTOROLA FAST SRAM

PACKAGE DIMENSIONS

CASE 810B-03 300 MIL SOJ 28 LEAD



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
- DIMENSION A & B DO NOT INCLUDE MOLD PROTRUSION. MOLD PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- 3. CONTROLLING DIMENSION: INCH.
- 4. DIM R TO BE DETERMINED AT DATUM -T-.

	INC	HES	MILLIN	METERS
DIM	MIN	MAX	MIN	MAX
Α	0.720	0.730	18.29	18.54
В	0.295	0.305	7.50	7.74
С	0.128	0.148	3.26	3.75
D	0.015	0.020	0.39	0.50
E	0.088	0.098	2.24	2.48
F	0.026	0.032	0.67	0.81
G	0.050	BSC	1.27	BSC
Н	_	0.020	_	0.50
K	0.035	0.045	0.89	1.14
L	0.025	BSC	0.64	BSC
M	0°	10°	0°	10°
N	0.030	0.045	0.76	1.14
P	0.330	0.340	8.38	8.64
R	0.260	0.270	6.60	6.86
S	0.030	0.040	0.77	1.01

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